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METHOD OF TESTING SEMICONDUCTOR
INTEGRATED CIRCUIT AND PROBE CARD

Abstract:

PROBLEM TO BE SOLVED: To remove defective semiconductor chips on a semiconductor wafer, when the en-bloc burn-in in the form of a wafer.

SOLUTION: Integrated circuit chips 2 on a semiconductor wafer 1 are tested and burnt-in in the form of a wafer, using a probe card having power voltage feed lines 4 and ground lines 5 divided per row and column and disposed mutually crosswise. For defective chips found, the voltages on corresponding power voltage feed lines 4 and ground lines 5 are replaced to feed negative power voltages, conductors 17 between electrodes 14 for feeding the power voltages and internal circuits are cut off to stop feeding the power voltages to the internal circuits, while the power voltages feed to the internal circuits of other: good chips are kept.

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